









ProLight PBVP-4FWE-F1GR-P 4W Power LED Technical Datasheet Version: 1.0

# **ProLight Opto ProEngine Series**

#### **Features**

- · High flux density of lighting source
- Good color uniformity
- · RoHS compliant
- More energy efficient than incandescent and most halogen lamps
- · Long lifetime
- · AEC-Q102 compliant
- · SAE/ECE Compliant

## **Main Applications**

- · Bicycle Lamps
- · Exterior Automotive Lighting
- · Floodlight

Automotive

- · Bending Light
- · Daytime Running Light

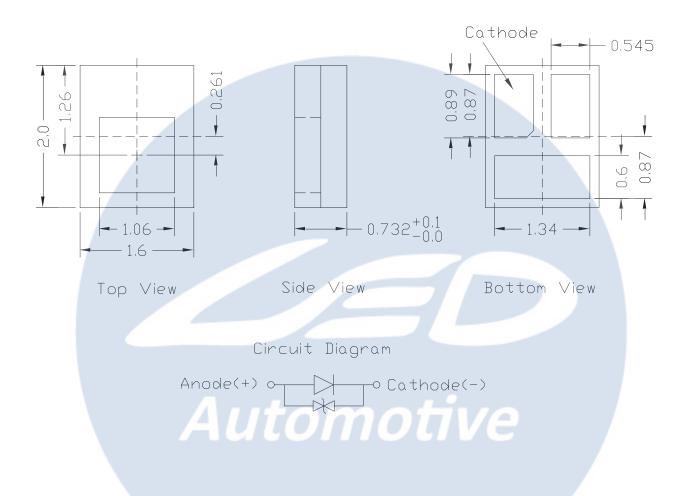
#### Introduction

• The input power is 4 Watt, the multi-chip ultra high power ProEngine Serie delivers never before seen luminous flux output from a single emitter. The superficial illuminating nature of ProEngine makes them the preference bicycle lamps, typical applications include exterior automotive lighting Bending and Daytime Running Light.



#### **Emitter Mechanical Dimensions**

Unit: mm



#### Notes:

- 1. Drawing not to scale.
- 2. All dimensions are in millimeters.
- 3. Unless otherwise indicated, tolerances are  $\pm$  0.1mm.
- 4. Please do not solder the emitter by manual hand soldering, otherwise it will damage the emitter.
- 5. Please do not use a force of over 0.3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

<sup>\*</sup>The appearance and specifications of the product may be modified for improvement without notice.



## Flux Characteristics, $T_j = 25^{\circ}C$

Dadiation		Dort Number		Luminous Flux Φ <sub>ν</sub> (lm)			
Radiation Color		Part Number	@1000mA		Refer @	Refer @1200mA	
Pattern		Emitter	Min.	Тур.	Min.	Тур.	
Lambertian	White	PBVP-4FWE-F1GR-P	375	430	435	500	

- ProLight maintains a tolerance of ± 7% on flux and power measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

### **Electrical Characteristics, T<sub>1</sub> = 25°C**

		Forward	Voltage V	′ <sub>F</sub> (V)	Real Thermal	Electrical Thermal
		@1000mA		Refer @1200mA	Resistance Junction to	Resistance Junction to
Color	Min.	Тур.	Max.	Тур.	Slug (°C/W)	Slug (°C/W)
White	2.8	3.1	3.4	3.2	4.7	2.9

ProLight maintains a tolerance of ± 0.1V for Voltage measurements.

## Optical Characteristics at 1000mA, T<sub>J</sub> = 25°C

Radiation	Color	Color Temperature CCT			
Pattern	00101	Min.	Тур.	Max.	2 θ <sub>1/2</sub>
		5430 K	5555 K	5680 K	120
Lambertian	\\/hito	5680 K	5825 K	5970 K	120
Lambertian	White	5970 K	6150 K	6330 K	120
		6330 K	6545 K	6760 K	120

<sup>•</sup> ProLight maintains a tolerance of ± 5% for CCT measurements.



# **Absolute Maximum Ratings**

Parameter	White
Max DC Forward Current (mA)	1500
Peak Pulsed Forward Current (mA)	1500 (less than 1/10 duty cycle@1KHz)
LED Junction Temperature	150°C
Junction Temperature for short time applications*	175°C
Operating Temperature	-40°C - 125°C
Storage Temperature	-40°C - 125°C
Soldering Temperature	JEDEC 020c 260°C
Allowable Reflow Cycles	3
Reverse Voltage	Not designed to be driven in reverse bias
ESD withstand voltage(kV) acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	up to 8

Note: \* The LED chip exhibits excellent performance but slight package discoloration occurs at highest temperatures. Exemplary median lifetime for  $T_J = 175^{\circ}C$  is 100h.





#### **Photometric Luminous Flux Bin Structure**

Color	Bin Code	Minimum Photometric Flux (Im)	Maximum Photometric Flux (Im)	Available Color Bins
	S3	375	395	[1]
	S4	395	415	All
	S5	415	435	All
White	S6	435	460	All
	S7	460	485	[1]
	S8	485	510	[1]
	S9	510	535	[1]

- ProLight maintains a tolerance of ± 7% on flux and power measurements.
- The flux bin of the product may be modified for improvement without notice.
- [1] The rest of color bins are not 100% ready for order currently. Please ask for quote and order Possibility.
- At least two adjacent bins are allowed.

#### **Forward Voltage Bin Structure**

Color	Bin Code	Minimum Voltage (V)	Maximum Voltage (V)
White	B	2.8	3.1
	C	3.1	3.4

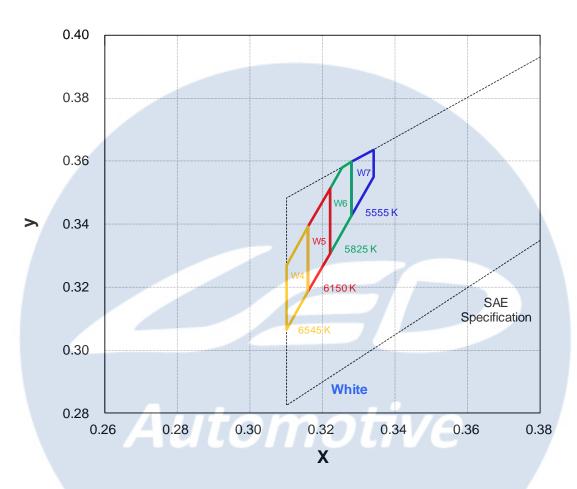
ProLight maintains a tolerance of ± 0.1V for Voltage measurements.

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.



#### **Color Bin**

**White Binning Structure Graphical Representation** 



#### White Bin Structure

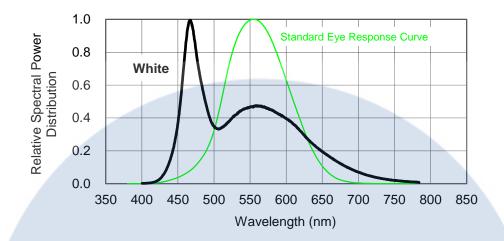
Bin Code	x	у	Typ. CCT (K)	Bin Code	x	у	Typ. CCT (K)
	0.3281	0.3597			0.3160	0.3391	
W7	0.3281	0.3428	5555	W5	0.3160	0.3186	6150
VV /	0.3342	0.3549	5555	VV 5	0.3221	0.3307	0130
	0.3342	0.3635			0.3221	0.3512	
	0.3221	0.3512			0.3100	0.3270	
	0.3221	0.3307		W4	0.3100	0.3065	6545
W6	0.3281	0.3428	5825	V V 4	0.3160	0.3186	0040
	0.3281	0.3597			0.3160	0.3391	
	0.3254	0.3578					

- Tolerance on each color bin (x , y) is ± 0.005
- At least two adjacent bins are allowed.



# Color Spectrum, $T_J = 25^{\circ}C$

1. White



Automotive



### **Junction Temperature Relative Characteristics**

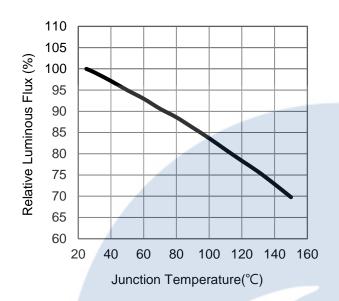


Fig 1. Junction Temperature vs.
Relative Luminous Flux at 1000mA.

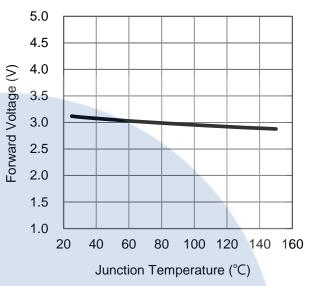


Fig 2. Junction Temperature vs. Forward Voltage at 1000mA.

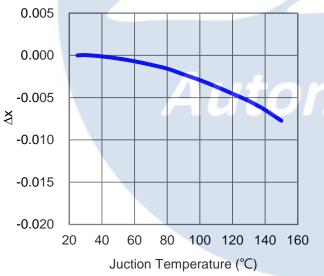


Fig 3. Junction Temperature vs. Chromaticity Coordinate  $\Delta x$  at 1000mA.

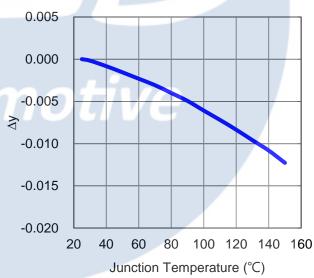


Fig 4. Junction Temperature vs. Chromaticity Coordinate  $\Delta y$  at 1000mA.



#### **Forward Current Relative Characteristics**

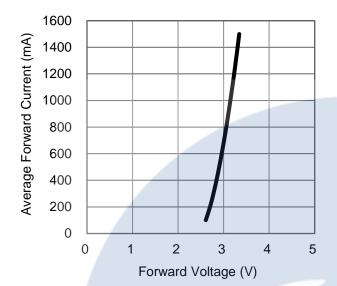


Fig 5. Forward Voltage vs. Forward Current at T<sub>.1</sub>=25°C.

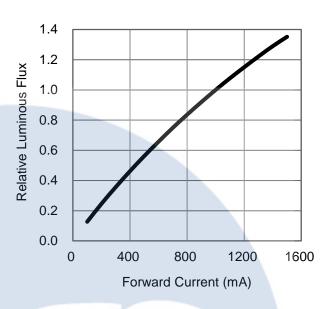


Fig 6. Forward Current vs. Relative Luminous Flux at  $T_J=25$ °C.



Fig 7. Forward Current vs. Chromaticity Coordinate  $\Delta x$  at  $T_J=25^{\circ}C$ .

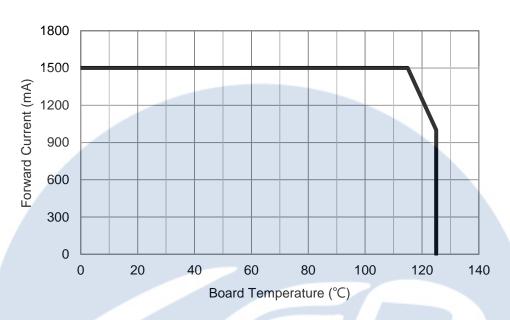


Fig 8. Forward Current vs. Chromaticity Coordinate  $\Delta y$  at  $T_J=25^{\circ}C$ .

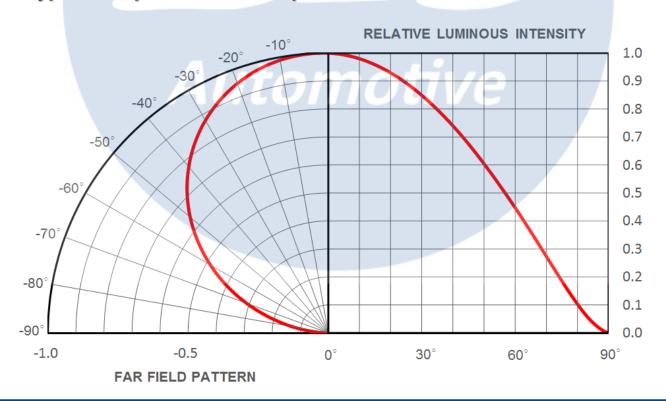


### **Board Temperature vs. Maximum Forward Current**

**Maximum Forward Current** 



## **Typical Representative Spatial Radiation Pattern**



2025/04 DS-1978



## **Moisture Sensitivity Level – JEDEC Level 1**

				Soak Req	uirements	
Level	Floor Life		Floor Life Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA

- The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

				Soak Req	uirements		
Level	Floor Life		Stan	dard	Accelerated	Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions	
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA	
2	1 year	≤30°C / 60% RH	168 +5/-0	85°C / 60% RH	NA	NA	
2a	4 weeks	≤30°C / 60% RH	696 +5/-0	30°C / 60% RH	120 +1/-0	60°C / 60% RH	
3	168 hours	≤30°C / 60% RH	192 +5/-0	30°C / 60% RH	40 +1/-0	60°C / 60% RH	
4	72 hours	≤30°C / 60% RH	96 +2/-0	30°C / 60% RH	20 +0.5/-0	60°C / 60% RH	
5	48 hours	≤30°C / 60% RH	72 +2/-0	30°C / 60% RH	15 +0.5/-0	60°C / 60% RH	
5a	24 hours	≤30°C / 60% RH	48 +2/-0	30°C / 60% RH	10 +0.5/-0	60°C / 60% RH	
6	Time on Label (TOL)	≤30°C / 60% RH	Time on Label (TOL)	30°C / 60% RH	NA	NA	



### Reliability testing in accordance with AEC-Q102

The development of this product included extensive operational life-time testing and environmental testing. Table 1 summarizes the tests applied and cumulative test results obtained from testing performed in accordance with AEC-Q102.

Table 1. Operating life, mechanical and environmental tests performed on it's package in accordance with AEC-Q102.

#	STRESS	ABV	Conditions	Duration	Failure Criteria	Rejects
1	Pre- and Post-Stress Electrical Test	TEST	Test is performed as specified in the applicable stress reference at room temperature.	N/A	See notes [2]	0
<u>A1</u>	Pre-conditioning	PC	Soak Tamb = 85 °C, RH = 85% Reflow soldering	N/A	See notes [2]	0
<u>A2a</u>	Wet High Temperature Operating Life	WHTOL 1	Tambient = 85 °C / 85% RH IF = max. DC [1]	1000 hours	See notes [2]	0
<u>A3a</u>	Power Temperature Cycling	PTC	-40°C to 125°C, 10 minutes dwell, 20 minutes transfer (1 hour cycle), 2 minutes ON/2 minutes OFF, IF = max. DC [1]	1000 hours	See notes [2]	0
<u>A4</u>	Temperature Cycling	TC	-40°C to 125°C,15 minutes dwell	1000 cycles	See notes [2]	0
<u>B1a</u>	High Temperature Operating Life	HTOL1	Tsolder =85°C, IF = max. DC [1]	1000 hours	See notes [2]	0
<u>B1b</u>	High Temperature Operating Life	HTOL2	Maximum specified Tsolder, IF = max. DC [1]	1000 hours	See notes [2]	0
<u>C9</u>	Thermal Resistance	TR	All qualification parts submitted for testing	N/A	See notes [2]	0
C10	Solderability	SD	245 °C ± 5 °C	3s	See notes [3]	0
<u>C12</u>	Hydrogen Sulphide	H2S	Corrosion class A: (preferred) Duration 336 h at 40 °C and 90% RH. H2S concentration: 15ppm	336 hours	See notes [2]	0
<u>E3</u>	Electrostatic Discharge Human Body Model	НВМ	ANSI/ESDA/JEDEC JS-001	N/A	See notes [3]	0
<u>G2</u>	Vibration Variable Frequency	VVF	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis	N/A	See notes [3]	0
<u>G3</u>	Mechanical Shock	MS	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis	N/A	See notes [3]	0

#### Notes:

1. Depending on the maximum derating curve.

2. Criteria for judging failure

I.	T (0 1111	Criteria for Judgement		
Item	Test Condition	Min.	Max.	
Forward Voltage (V <sub>F</sub> )	$I_F = max DC$		Initial Level x 1.1	
Luminous Flux or Radiometric Power (Φ <sub>V</sub> )	I <sub>F</sub> = max DC	Initial Level x 0.8		
Reverse Current (I <sub>R</sub> )	$V_R = 5V$		50 µA	

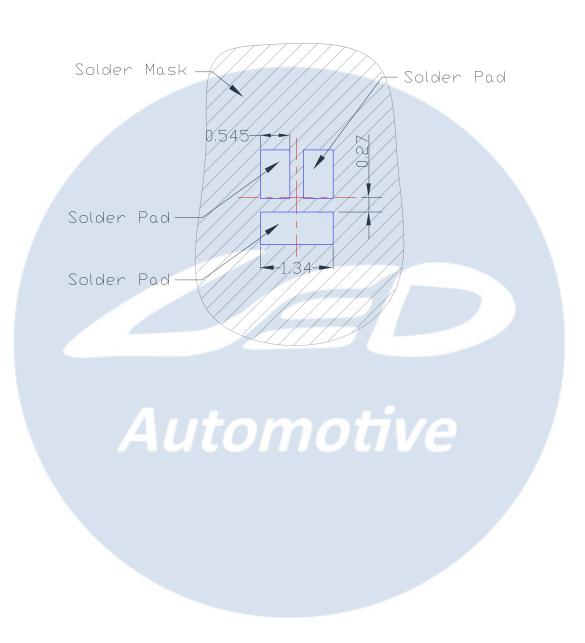
<sup>\*</sup> The test is performed after the LED is cooled down to the room temperature.

<sup>3.</sup> A failure is an LED that is open or shorted.



# **Recommended Solder Pad Design**

**Standard Emitter** 

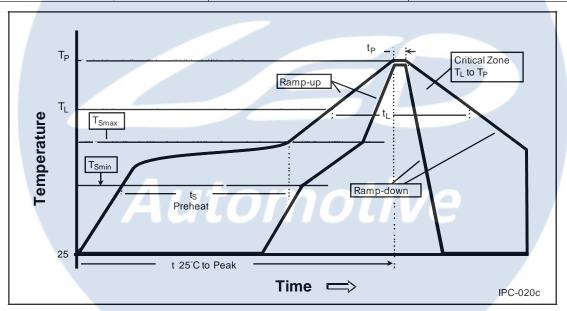


• All dimensions are in millimeters.



#### **Reflow Soldering Condition**

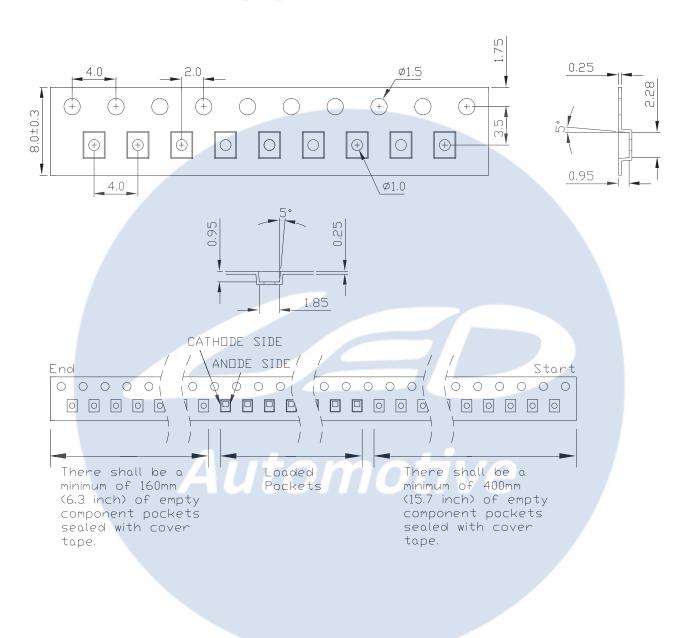
Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate	3°C / second max.	3°C / second max.
(T <sub>Smax</sub> to T <sub>P</sub> )	3 C/ Second max.	3 C/ Second Max.
Preheat		
<ul><li>– Temperature Min (T<sub>Smin</sub>)</li></ul>	100°C	150°C
<ul><li>Temperature Max (T<sub>Smax</sub>)</li></ul>	150°C	200°C
– Time (t <sub>Smin</sub> to t <sub>Smax</sub> )	60-120 seconds	60-180 seconds
Time maintained above:		
– Temperature (T <sub>L</sub> )	183°C	217°C
– Time (t <sub>1</sub> )	60-150 seconds	60-150 seconds
Peak/Classification Temperature (T <sub>P</sub> )	240°C	260°C
Time Within 5°C of Actual Peak	10-30 seconds	20-40 seconds
Temperature (t <sub>p</sub> )	To-so seconds	20-40 Seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind
  of solder pastes may cause a reliability problem to LED.
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a
  double-head soldering iron should be used. It should be confirmed beforehand whether the
  characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.



## **Emitter Reel Packaging**



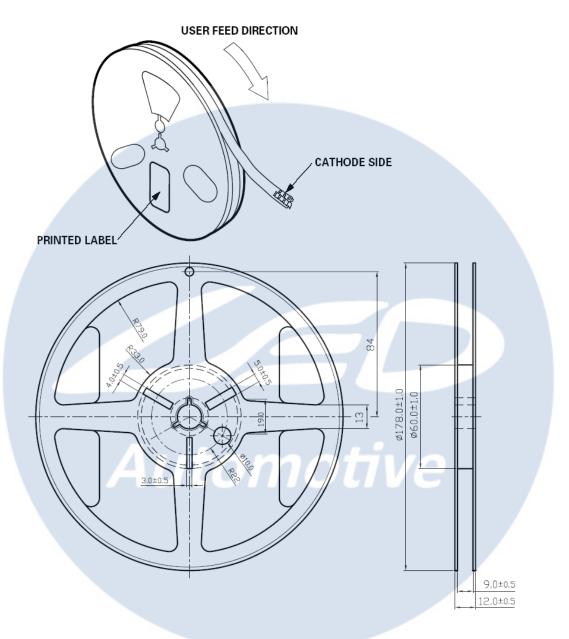
#### Notes:

- 1. Drawing not to scale.
- 2. All dimensions are in millimeters.
- 3. Unless otherwise indicated, tolerances are  $\pm$  0.1mm.

2025/04 DS-1978



# **Emitter Reel Packaging**



#### Notes:

- 1. Empty component pockets sealed with top cover tape.
- 2. 2000 pieces per reel.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.



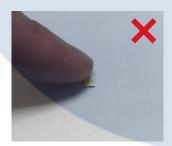
#### **Precaution for Use**

- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- Do not use solder pastes with post reflow flux residue>47%. (58Bi-42Sn eutectic alloy, etc) This kind of solder pastes may cause a reliability problem to LED.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets. http://www.prolightopto.com/

#### **Handling of Lens LEDs**

Notes for handling of lens LEDs

- Please do not use a force of over 0.3kgf impact or pressure on the lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- Please do not mold over the lens with another resin. (epoxy, urethane, etc)







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- 2. A critical component is any component of a life support device or system whose failure can reasonably be expected to cause the failure of the device or system, or to affect its safety or effectiveness.